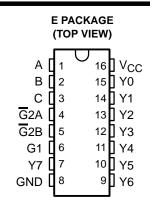
- Inputs Are TTL-Voltage Compatible
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Designed Specifically for High-Speed Memory Decoders and Data-Transmission Systems
- Incorporates Three Enable Inputs to Simplify Cascading and/or Data Reception
- Balanced Propagation Delays
- ±24-mA Output Drive Current
- Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015



description/ordering information

The CD74ACT238 decoder/demultiplexer is designed for high-performance memory-decoding and data-routing applications that require very short propagation-delay times. In high-performance memory systems, this decoder can be used to minimize the effects of system decoding. When employed with high-speed memories utilizing a fast enable circuit, the delay times of this decoder and the enable time of the memory usually are less than the typical access time of the memory. This means that the effective system delay introduced by the decoder is negligible.

The conditions at the binary-select inputs and the three enable inputs select one of eight output lines. Two active-low and one active-high enable inputs reduce the need for external gates or inverters when expanding. A 24-line decoder can be implemented without external inverters, and a 32-line decoder requires only one inverter. An enable input can be used as a data input for demultiplexing applications (see Application Information).

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
-55°C to 125°C	PDIP – E	Tube	CD74ACT238E	CD74ACT238E	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



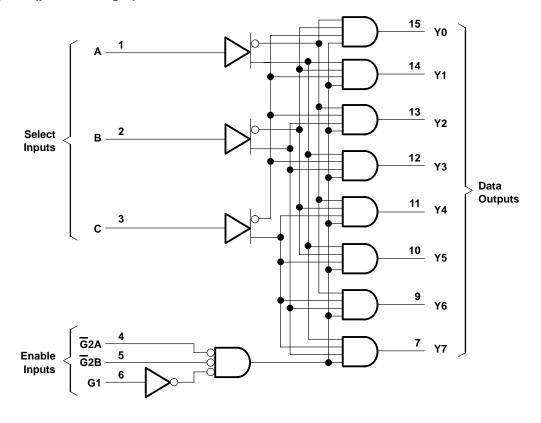
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FUNCTION TABLE

ENA	BLE INF	PUTS	SEL	ECT INP	UTS				OUTI	PUTS			
G1	G2A	G2B	С	В	Α	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
Х	Н	Х	Х	Х	Х	L	L	L	L	L	L	L	L
Х	X	Н	Χ	X	X	L	L	L	L	L	L	L	L
L	X	X	Х	Χ	X	L	L	L	L	L	L	L	L
Н	L	L	L	L	L	Н	L	L	L	L	L	L	L
Н	L	L	L	L	Н	L	Н	L	L	L	L	L	L
Н	L	L	L	Н	L	L	L	Н	L	L	L	L	L
Н	L	L	L	Н	Н	L	L	L	Н	L	L	L	L
Н	L	L	Н	L	L	L	L	L	L	Н	L	L	L
Н	L	L	Н	L	Н	L	L	L	L	L	Н	L	L
Н	L	L	Н	Н	L	L	L	L	L	L	L	Н	L
Н	L	L	Н	Н	Н	L	L	L	L	L	L	L	Н

logic diagram (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 6 V
Input clamp current, I_{IK} ($V_I < 0 \text{ V or } V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 V or V _O > V _{CC}) (see Note 1)	±50 mA
Continuous output current, I_O ($V_O > 0$ V or $V_O < V_{CC}$)	±50 mA
Continuous current through V _{CC} or GND	±200 mA
Package thermal impedance, θ_{JA} (see Note 2)	67°C/W
Storage temperature range, T _{stq}	. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		T _A = 25°C		–55°C to 125°C				UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
Vcc	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
V _{IH}	High-level input voltage	2		2		2		V
V _{IL}	Low-level input voltage		0.8		8.0		0.8	V
٧ _I	Input voltage	0	VCC	0	VCC	0	VCC	V
٧o	Output voltage	0	VCC	0	VCC	0	VCC	V
IOH	High-level output current		-24		-24		-24	mA
loL	Low-level output current		24		24		24	mA
Δt/Δν	Input transition rise or fall rate		10		10		10	ns/V

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		VCC	T _A = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT	
			MIN I	MAX	MIN	MAX	MIN	MAX			
		I _{OH} = -50 μA	4.5 V	4.4		4.4		4.4			
Vari	V _I = V _{IH} or V _{IL}	$I_{OH} = -24 \text{ mA}$	4.5 V	3.94		3.7		3.8		V	
VOH	I vi = viH or vil	$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V			3.85				V	
		$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V					3.85			
	VI = VIH or VIL	I _{OL} = 50 μA	4.5 V		0.1		0.1		0.1	0.1	
Var		I _{OL} = 24 mA	4.5 V		0.36		0.5		0.44 V		
VOL		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				1.65			v	
		I _{OL} = 75 mA [†]	5.5 V						1.65		
lį	$V_I = V_{CC}$ or GND		5.5 V		±0.1		±1		±1	μΑ	
ICC	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		8		160		80	μΑ	
ΔlCC [‡]	$V_{I} = V_{CC} - 2.1 \text{ V}$		4.5 V to 5.5 V		2.4		3		2.8	mA	
C _i					10		10		10	pF	

[†] Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C. ‡ Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

ACT INPUT LOAD TABLE

INPUT	UNIT LOAD
A, B, or C	0.83
G2A or G2B	1
G1	0.42

Unit Load is ΔI_{CC} limit specified in electrical characteristics table (e.g., 2.4 mA at 25°C).

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°(125		–40°C to 85°C		UNIT
	(1141 01)	(6611 61)	MIN	MAX	MIN	MAX	
^t PLH	A, B, C	Any Y	3.9	15.6	4	14.2	ns
tPHL	А, В, С	Ally I	3.9	15.6	4	14.2	115
^t PLH	04	Any V	3.4	13.6	3.5	12.4	nc
^t PHL	G1	Any Y	3.4	13.6	3.5	12.4	ns
t _{PLH}	<u>G</u> 2A, <u>G</u> 2B	Any V	3.6	14.2	3.7	12.9	20
^t PHL	GZA, GZB	Any Y	3.6	14.2	3.7	12.9	ns

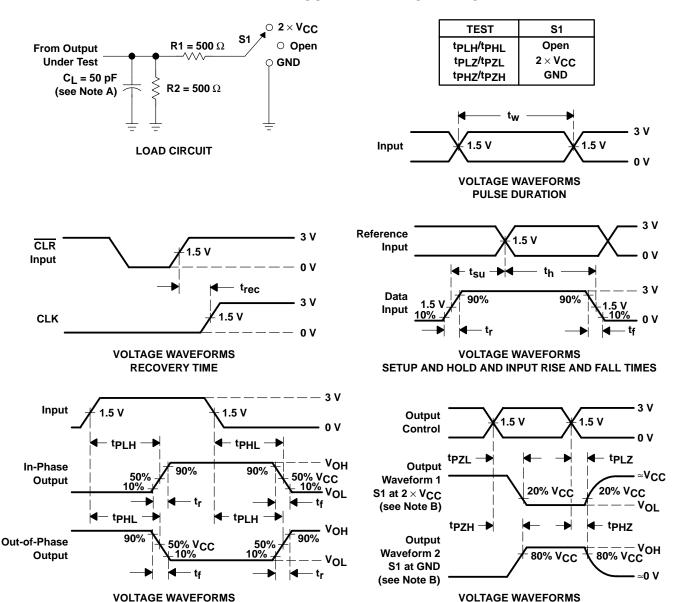
operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TYP	UNIT
C _{pd}	Power dissipation capacitance	110	pF



OUTPUT ENABLE AND DISABLE TIMES

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 3 \ ns$, $t_f = 3 \ ns$. Phase relationships between waveforms are arbitrary.
- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLH and tpHL are the same as tpd.
- G. t_{PZL} and t_{PZH} are the same as t_{en} .
- H. tpLZ and tpHZ are the same as tdis.
- I. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



APPLICATION INFORMATION

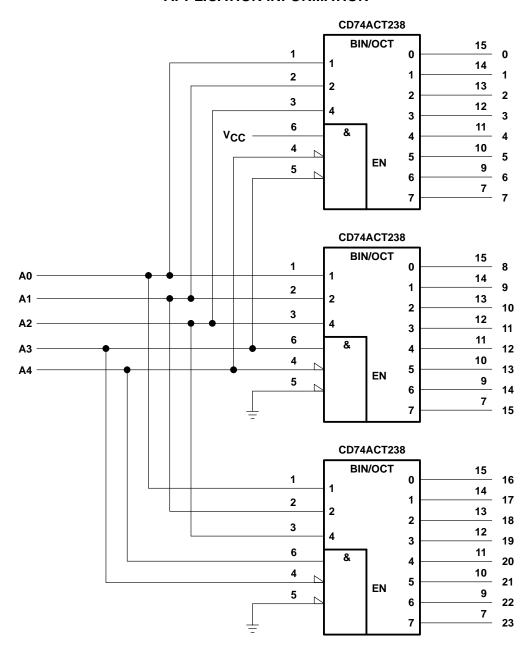


Figure 2. 24-Bit Decoding Scheme



APPLICATION INFORMATION CD74ACT238 BIN/OCT 15 0 A0 -14 1 2 A1 -2 13 2 3 12 A2 -3 6 11 & 4

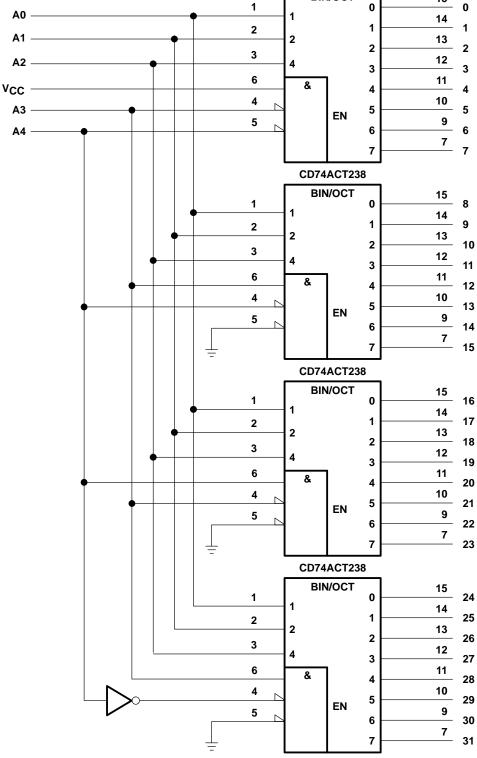


Figure 3. 32-Bit Decoding Scheme





PACKAGE OPTION ADDENDUM

12-Jan-2006

PACKAGING INFORMATION

www ti com

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD74ACT238E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74ACT238EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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